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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10027919	FILING DATE 12/20/2001	CLASS 205	SUBCLASS 291	GAU 1741	EXAMINER <i>Wong</i>
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**APPLICANTS: Seita Masaru; Tsuchida Hideki; Hayashi Shinjiro;

1753

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 2000-387865 12/20/2000

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no
ATTORNEY DOCKET NO 51343		
TITLE : Electrolytic copper plating solution and method for controlling the same U.S.DEP'T. OF COMM /PAT. & TM-PTO-436L(Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		Primary Examiner
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	
TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner
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